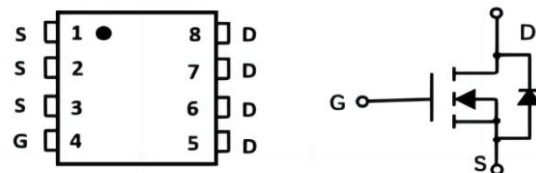
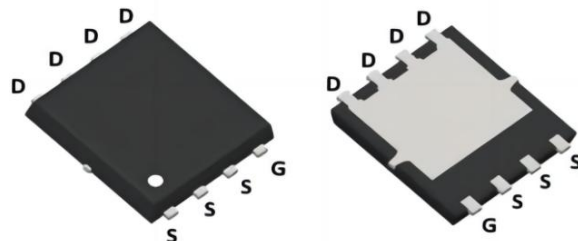


## N-Channel Enhancement Mode MOSFET

### Features

- $R_{DS(ON)}@10V < 7.5m\Omega$  (Typ.  $5m\Omega$ )
- $I_D = 90A$
- Fast Switching Speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

$BV_{DSS}, T_A=25^\circ C$	$R_{DS(ON)}, typ@10V$	$I_D, T_A=25^\circ C$
100	$5m\Omega$	90A



### Applications

- Power Management in DC/DC Converters
- USB Power Delivery(USB PD)

PDFN5x6-8L

### Absolute Maximum Ratings( $T_J=25^\circ C$ , unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		$V_{DSS}$	100	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$T_C=25^\circ C$	$I_D$	90	A
	$T_C=100^\circ C$		62	
Pulse Drain Current Tested	$T_C=25^\circ C$	$I_{DM}$	360	A
Maximum Power Dissipation	$T_C=25^\circ C$	$P_D$	89	W
	$T_C=100^\circ C$		36	
Maximum Junction Temperature		$T_J$	150	$^\circ C$
Storage Temperature Range		$T_{STG}$	$-55 \sim +150$	$^\circ C$
Avalanche Current, Single Pulse <sup>(2)</sup>	$L=0.1mH$	$I_{AS}$	41	A
Avalanche Energy, Single Pulse <sup>(2)</sup>	$L=0.1mH$	$E_{AS}$	84	mJ

### Thermal Characteristics

Parameter	Symbol	Limit	Unit
Thermal Resistance-Junction to Case	$R_{J\theta C}$	1.4	$^\circ C/W$
Thermal Resistance-Junction to Ambient <sup>(3)</sup>	$R_{J\theta A}$	50	$^\circ C/W$

Note(1):Max. Current is limited by binding wire

Note(2):UIS tested and pulse width are limited by maximum junction temperature  $150^\circ C$

Note(3):Surface Mounted on  $1in^2$  FR-4 board with 1oz

## Electrical Characteristics( $T_A=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>DS</sub> =250μA	100			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V,V <sub>GS</sub> =0V			1	μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>DS</sub> =250μA	2	3	4	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Drain-Source On-state Resistance <sup>(4)</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V,I <sub>DS</sub> =20A		5	7.5	mΩ
Forward Trans conductance	g <sub>fs</sub>	V <sub>DS</sub> =5V,I <sub>DS</sub> =10A		21.8		S
Dynamic Characteristics						
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V, f=1MHz		0.5		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V,V <sub>DS</sub> =50V, f=1MHz		2867		pF
Output Capacitance	C <sub>OSS</sub>			920		
Reverse Transfer Capacitance	C <sub>RSS</sub>			57		
Turn-on Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =25V, ID=1A,R <sub>G</sub> =3Ω		14.3		nS
Turn-on Rise Time	t <sub>r</sub>			4.3		
Turn-off Delay Time	t <sub>d(OFF)</sub>			32.1		
Turn-on Fall Time	t <sub>f</sub>			90.7		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =6V,V <sub>DS</sub> =50V, I <sub>D</sub> =20A		35		nC
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =50V, I <sub>D</sub> =20A		53.1		
Gate-Source Charge	Q <sub>gs</sub>			15.8		
Gate-Drain Charge	Q <sub>gd</sub>			15.1		
Source-Drain Characteristics						
Diode Forward Voltage <sup>(5)</sup>	V <sub>SD</sub>	I <sub>SD</sub> =2A,V <sub>GS</sub> =0V		0.7	1.1	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =10A,V <sub>R</sub> =50V, dI <sub>F</sub> /dt=100A/μs		47.6		nS
Reverse Recovery Charge	Q <sub>rr</sub>			66.6		nC

Note(4): Pulse test(pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ )

Note(5): Guaranteed by design, not subject to production testing

## Typical Characteristics

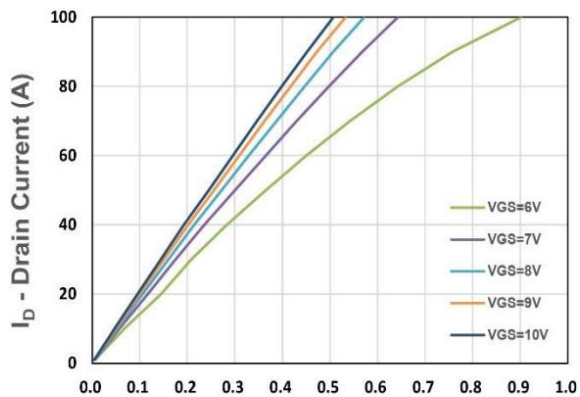


Figure 1. Output Characteristics

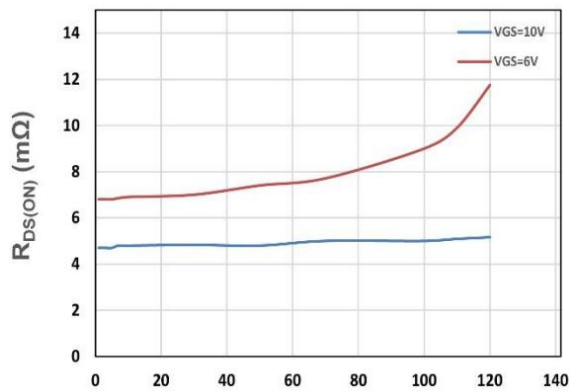


Figure 2. On-Resistance vs.  $I_D$

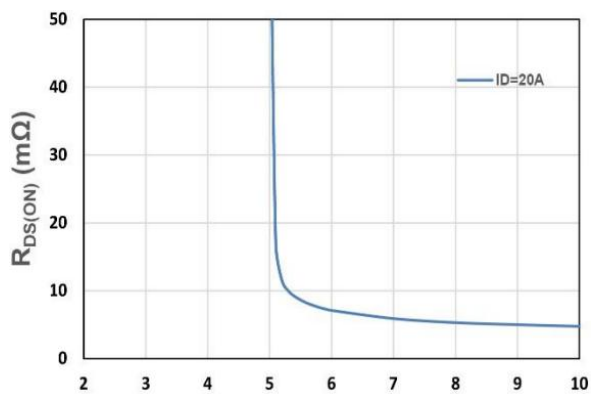


Figure 3. On-Resistance vs.  $V_{GS}$

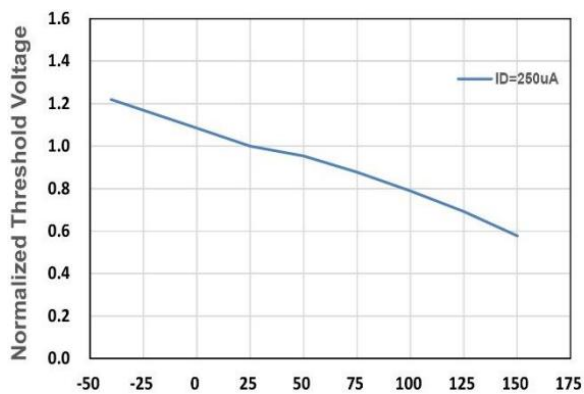


Figure 4. Gate Threshold Voltage

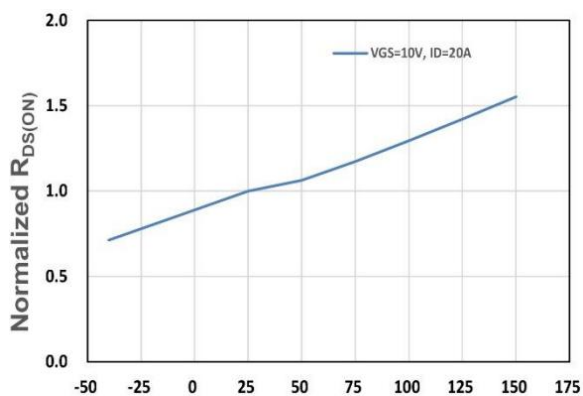


Figure 5. Drain-Source On Resistance

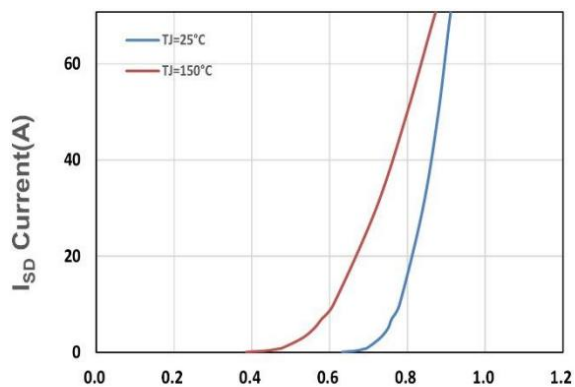
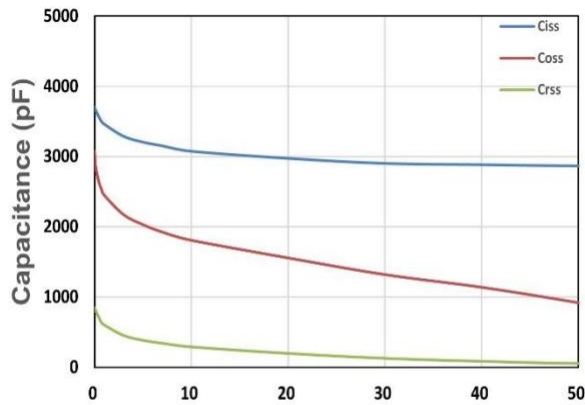
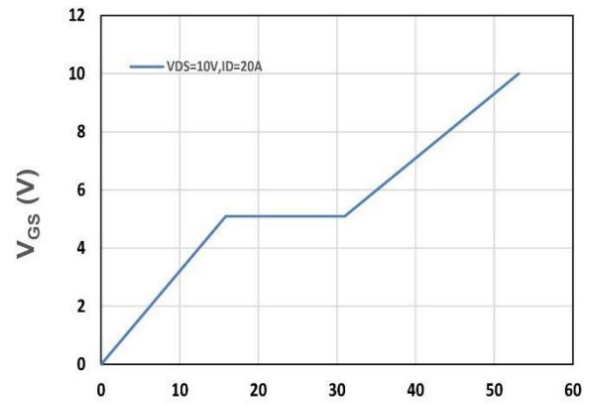


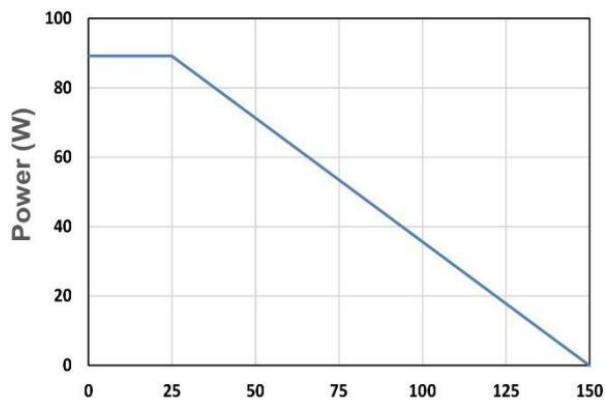
Figure 6. Source-Drain Diode Forward



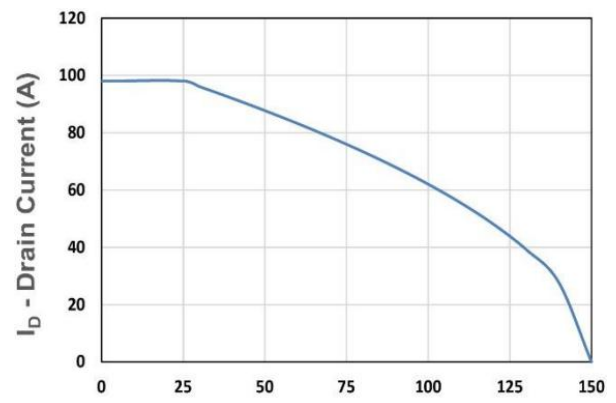
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 7. Capacitance



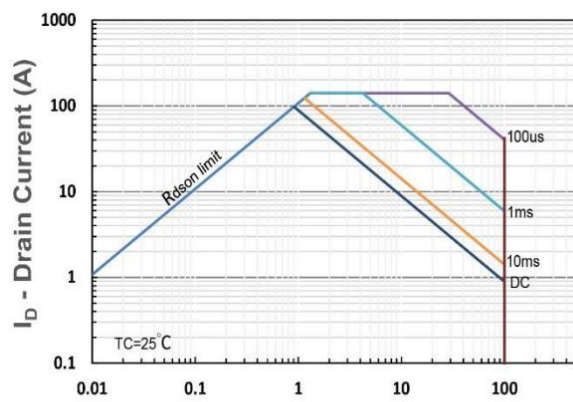
$Q_g$ , Total Gate Charge (nC)  
Figure 8. Gate Charge Characteristics



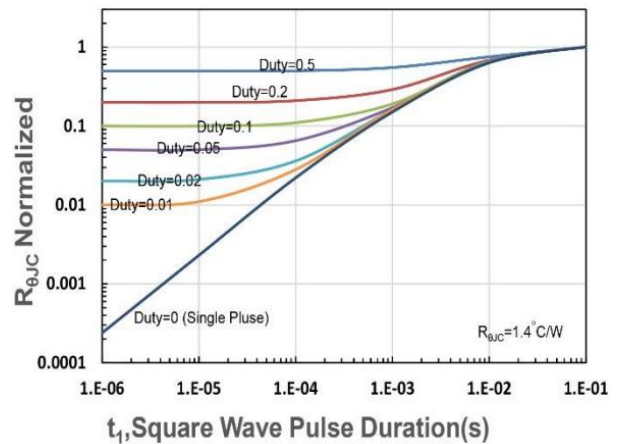
$T_c$  - Case Temperature (°C)  
Figure 9. Power Dissipation



$T_c$  - Case Temperature (°C)  
Figure 10. Drain Current



$V_{DS}$  - Drain-Source Voltage (V)  
Figure 11. Safe Operating Area

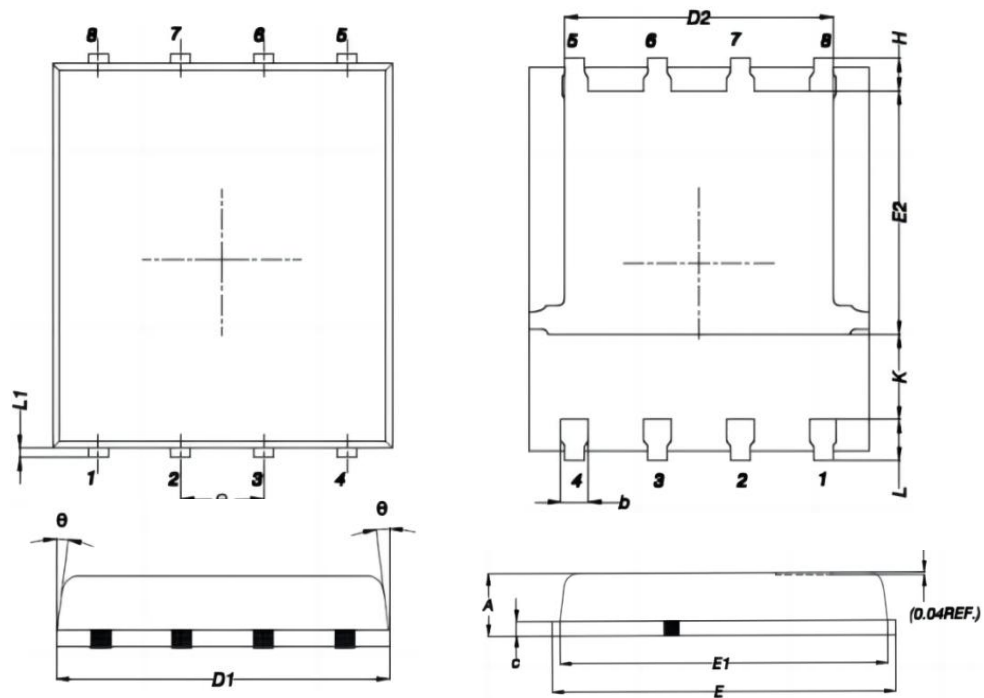


$t_1$ , Square Wave Pulse Duration(s)  
Figure 12.  $R_{\theta JC}$  Transient Thermal Impedance

## Package Information

PDFN5x6-8L

Dimensions in mm



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
$\theta$	12°	0°	12°	0°

## **Shikues Disclaimer**

### **1.Accuracy of Information and Right to Modify**

The information provided in this document is for reference only. Shikues reserves the right to make changes to this document and to the specifications of the products described herein at any time, without prior notice, for the purpose of improving reliability, function, design, or for any other reason. It is the customer's responsibility to obtain and verify the latest product information and specifications before making any final design, procurement, or usage decisions.

### **2.No Warranty**

Shikues makes no express or implied warranties, representations, or guarantees regarding the suitability of its products for any particular purpose.

Shikues assumes no liability for any assistance provided or for the design of customer products. All products are supplied "as is."

### **3.Intended Use and Limitation of Liability**

The products described in this document are intended for use in general-purpose electronic devices. They are neither designed nor tested nor authorized for use in transportation equipment or applications requiring high reliability. Unless expressly authorized in writing by Shikues, these products must not be used as critical components in life-support systems or any applications where failure could directly pose a risk to human life (including, but not limited to, medical devices, transportation systems, aerospace equipment, nuclear facilities, and safety-critical systems).

Shikues assumes no responsibility or liability for any consequences arising from the use of its products in unauthorized or unintended applications.

Neither Shikues nor its representatives shall be held liable for any resulting damages.

### **4.Intellectual Property**

This document does not grant any express or implied license—whether by estoppel, implication, or otherwise—to use any intellectual property rights of Shikues.